ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES

IPC-SM-784

Guidelines for Chip-on-Board Technology Implementation

ANSI/IPC-SM-784

A standard developed by IPC

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Developed by the Direct Chip Attachment Task Group of the Hybrid and Related Technologies Committee of IPC

APPROVED DECEMBER 20, 1990 BY

AMERICAN NATIONAL STANDARDS INSTITUTE

Users of this standard are encouraged to participate in the development of future revisions.

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Acknowledgment

Any Standard involving a complex technology draws material from a vast number of sources. While the principal members of the Direct Chip Attachment Task Group of the IPC Hybrid and Related Technologies Committee are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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